

VUE 400-P-NexGen SCANNING ACOUSTIC MICROSCOPE

Semiconductor Package Failure Analysis
voids · disbonds · cracks · delamination · internal defects

Customer Interface

Dual 22" HD LED Monitors

Fixtures

Tray Fixture

Instrumentation

Digital Pulser Receiver

Ultrasonic Digitizer (Max 12 GHz)

User Experience Elements

Dual JEDEC Trays

HD LED Lighting

Stainless Steel Tank

Maintenance Free Scan Axis

Motor:

Max Velocity:

Accuracy & Repeatability:

Quad Linear Servo

1500 mm/s

+/- 0.5 micron

Scan Length: 400 mm

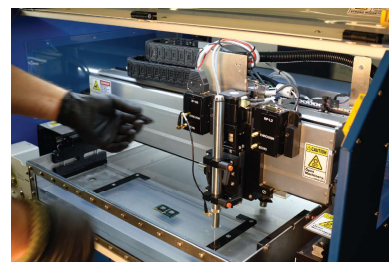
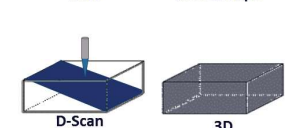
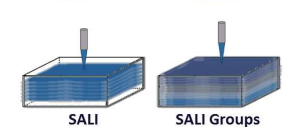
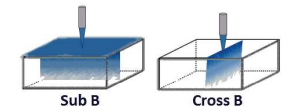
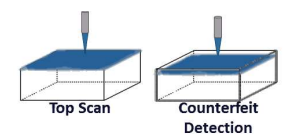
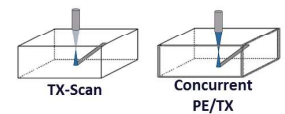
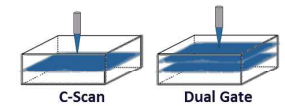
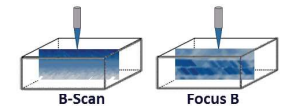
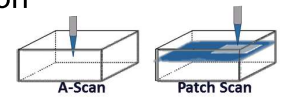
Step Length: 380 mm

Focus Length: 35 mm

C-Scan Area: 360 mm x 350 mm

T-Scan Area: 360 mm x 220 mm

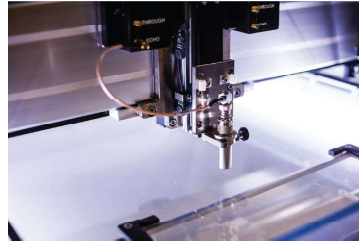
Weight: 250 Kg.



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Included Software Modes:

- Basic (user friendly)
- Advanced (detailed analysis)
- Production (automated scanning)
- Off-line Analysis (virtual scanning)



OKOS Digital Imaging System (ODIS)



VUE 250-P imaging power surpasses modern standards delivering premium FA Lab features to semiconductor fabrication facilities.

ODIS is the latest Acoustic Microscopy software with rich technical content built on current platforms and industry feedback.

Advanced analysis is provided through quantitative tools for measurement and classification of parts.

The Analysis version of ODIS allows non-scanning computers to virtually scan, view, and analyze data for simultaneous real-time analysis or post collection review.

- Counterfeit Detection
- Product Inspection
- Product Reliability
- Quality Control
- Process Validation
- Failure Analysis
- Vendor Qualification
- R&D

Application Specific Transducers

for the highest quality resolution.

Multiple transducer design for enhanced scan capability.

